

FEATURES

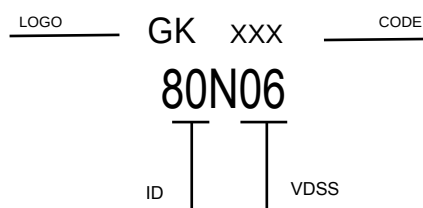
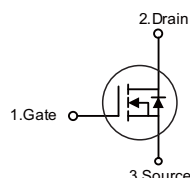
Super Low Gate Charge
100% EAS Guaranteed
Green Device Available
Excellent CdV/dt effect decline
Advanced high cell density Trench technology

DESCRIPTION

The 80N06 is the high cell density trenched N-ch MOSFETs, which provide excellent RDSON and gate charge for most of the synchronous buck converter applications.

The 80N06 meet the RoHS and Green Product requirement, 100% EAS guaranteed with full function reliability approved.

V_{DSS} 60 V
 I_D 80 A
 $R_{DS(ON)}$ 6.0m Ω



MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Absolute Maximum Ratings ($T_A = 25^\circ\text{C}$, unless otherwise noted)

Symbol	Parameter		Max.	Units
V_{DSS}	Drain-Source Voltage		60	V
V_{GSS}	Gate-Source Voltage		± 25	V
I_D	Continuous Drain Current	$T_C = 25^\circ\text{C}$	80	A
		$T_C = 100^\circ\text{C}$	52	A
I_{DM}	Pulsed Drain Current ^{note1}		320	A
EAS	Single Pulsed Avalanche Energy ^{note2}		169	mJ
P_D	Power Dissipation	$T_C = 25^\circ\text{C}$	108	W
$R_{\theta JC}$	Thermal Resistance, Junction to Case		1.4	$^\circ\text{C/W}$
T_J, T_{STG}	Operating and Storage Temperature Range		-55 to +175	$^\circ\text{C}$

Electrical characteristics ($T_J=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
Off Characteristic						
V _{(BR)DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =250μA	60	-	-	V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =60V, V _{GS} =0V,	-	-	1.0	μA
I _{GSS}	Gate to Body Leakage Current	V _{DS} =0V, V _{GS} =±20V	-	-	±100	nA
On Characteristics						
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =250μA	2	3	4	V
R _{DS(on)}	Static Drain-Source on-Resistance note3	V _{GS} =10V, I _D =30A	-	6	8	mΩ
Dynamic Characteristics						
C _{iss}	Input Capacitance	V _{DS} =30V, V _{GS} =0V, f=1.0MHz	-	4136	-	pF
C _{oss}	Output Capacitance		-	286	-	pF
C _{rss}	Reverse Transfer Capacitance		-	257	-	pF
Q _g	Total Gate Charge	V _{DS} =30V, I _D =30A, V _{GS} =10V	-	90	-	nC
Q _{gs}	Gate-Source Charge		-	9	-	nC
Q _{gd}	Gate-Drain(“Miller”) Charge		-	18	-	nC
Switching Characteristics						
t _{d(on)}	Turn-on Delay Time	V _{DS} =30V, I _D =30A, R _G =1.8Ω, V _{GS} =10V	-	9	-	ns
t _r	Turn-on Rise Time		-	7	-	ns
t _{d(off)}	Turn-off Delay Time		-	40	-	ns
t _f	Turn-off Fall Time		-	15	-	ns
Drain-Source Diode Characteristics and Maximum Ratings						
I _S	Maximum Continuous Drain to Source Diode Forward Current		-	-	80	A
I _{SM}	Maximum Pulsed Drain to Source Diode Forward Current		-	-	320	A
V _{SD}	Drain to Source Diode Forward Voltage	V _{GS} =0V, I _S =30A	-	-	1.2	V
trr	Body Diode Reverse Recovery Time	I _F =30A, dI/dt=100A/μs	-	33	-	ns
Qrr	Body Diode Reverse Recovery Charge		-	46	-	nC

Notes:1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

2. EAS condition : $T_J=25^\circ\text{C}$, $V_{DD}=30V$, $V_G=10V$, $L=0.5mH$, $R_g=25\Omega$, $I_{AS}=26A$

3. Pulse Test: Pulse Width $\leq 300\mu s$, Duty Cycle $\leq 0.5\%$

RATING AND CHARACTERISTIC CURVES

Figure1: Output Characteristics

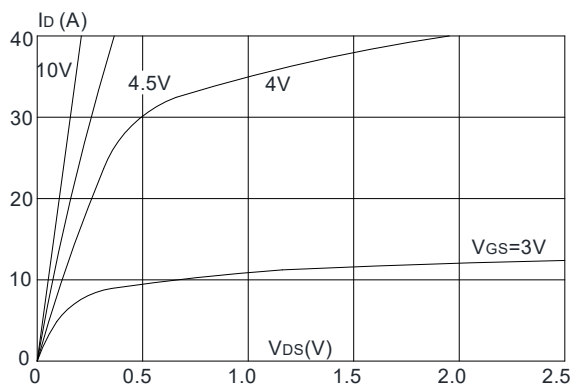


Figure 2: Typical Transfer Characteristics

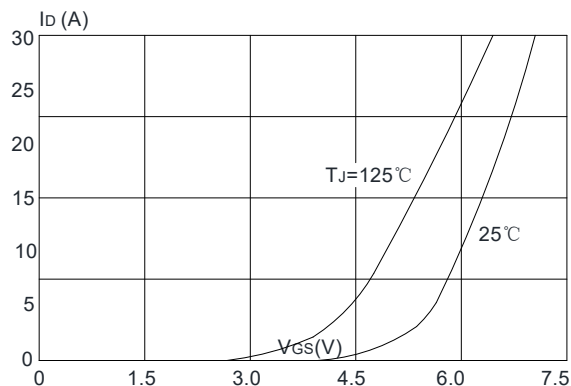


Figure 3: On-resistance vs. Drain Current

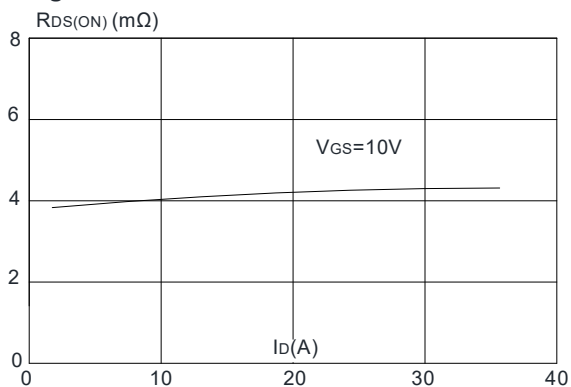


Figure 4: Body Diode Characteristics

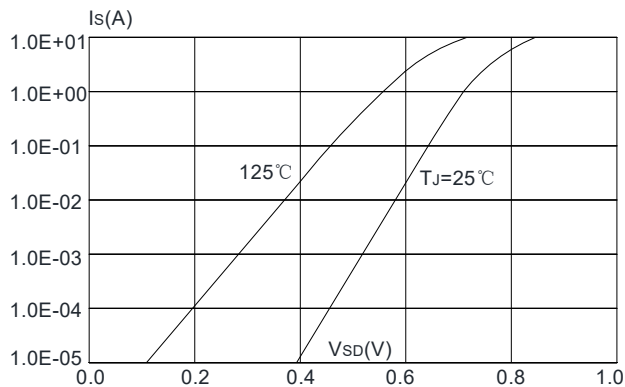


Figure 5: Gate Charge Characteristics

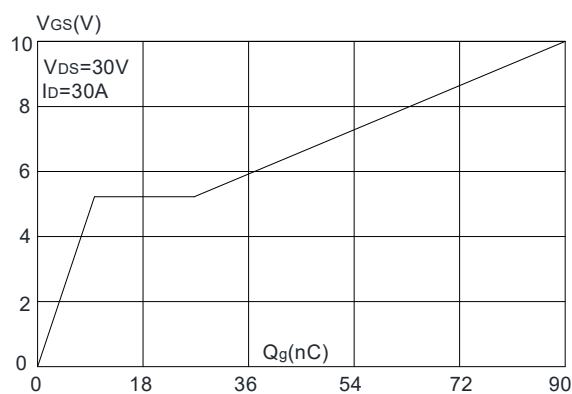
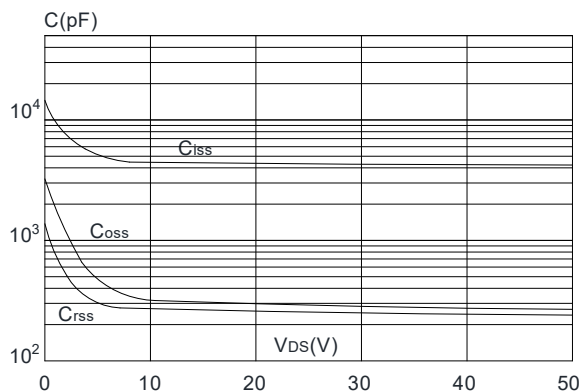


Figure 6: Capacitance Characteristics



RATING AND CHARACTERISTIC CURVES

Figure 7: Normalized Breakdown Voltage vs. Junction Temperature

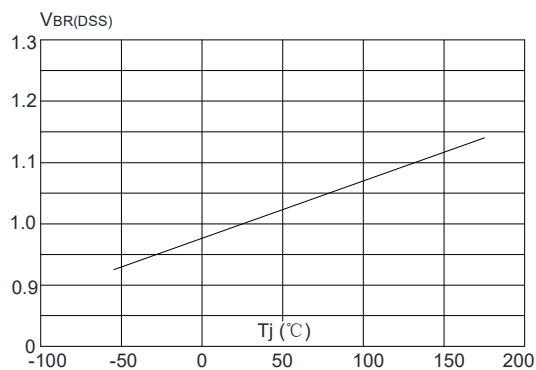


Figure 8: Normalized on Resistance vs. Junction Temperature

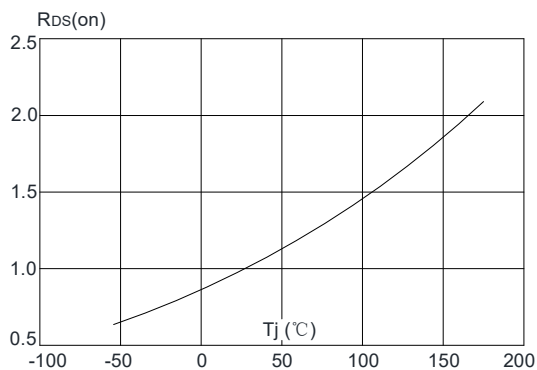


Figure 9: Maximum Safe Operating Area

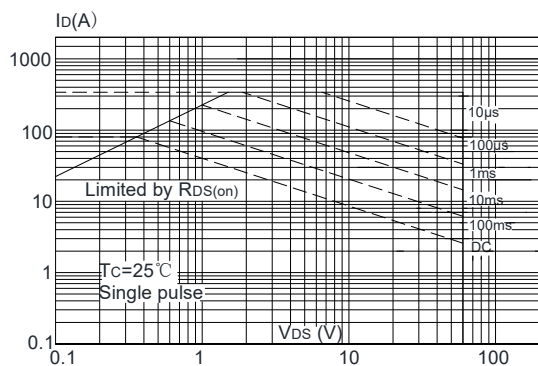


Figure 10: Maximum Continuous Drain Current vs. Case Temperature

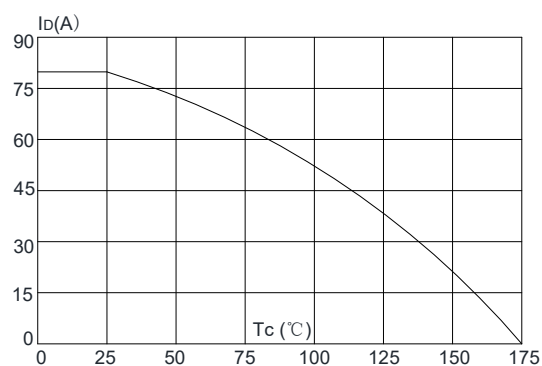
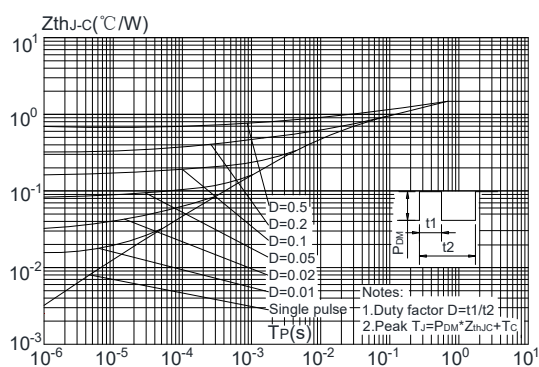
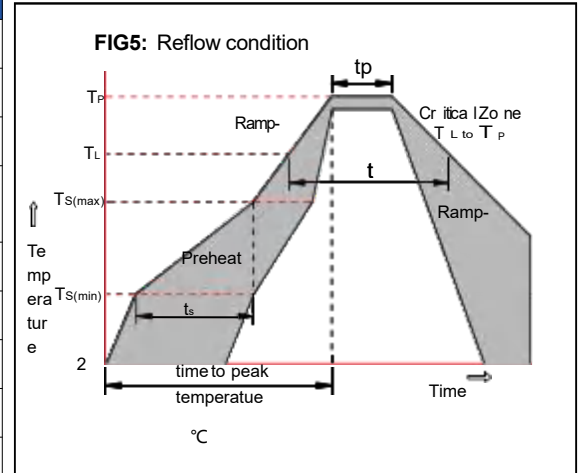


Figure.11: Maximum Effective Transient Thermal Impedance, Junction-to-Case



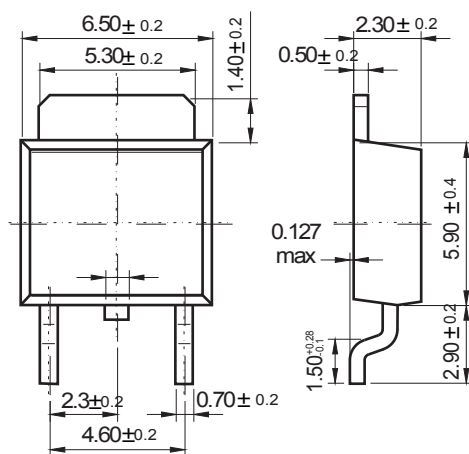
Soldering parameters

Reflow Condition		Pb-Free assembly (see as below)
Pre Heat	-Temperature Min ($T_{s(min)}$)	+150 °C
	-Temperature Max($T_{s(max)}$)	+200 °C
	-Time (Min to Max) (ts)	60-180 secs.
Average ramp up rate (Liquid us Temp (T_L) to peak)		3 °C/sec. Max
$T_{s(max)}$ to T_L - Ramp-up Rate		3 °C/sec. Max
Reflow	-Temperature(T_L)(Liquid us)	+217 °C
	-Temperature(t_L)	60-150 secs.
Peak Temp (T_P)		+260(+0/-5) °C
Time within 5 °C of actual Peak Temp (t_P)		30 secs. Max
Ramp-down Rate		6 °C/sec. Max
Time 25 °C to Peak Temp (T_P)		8 min. Max
Do not exceed		+260 °C

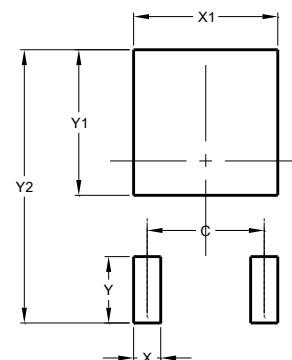


Package Dimensions & Suggested Pad Layout

TO-252

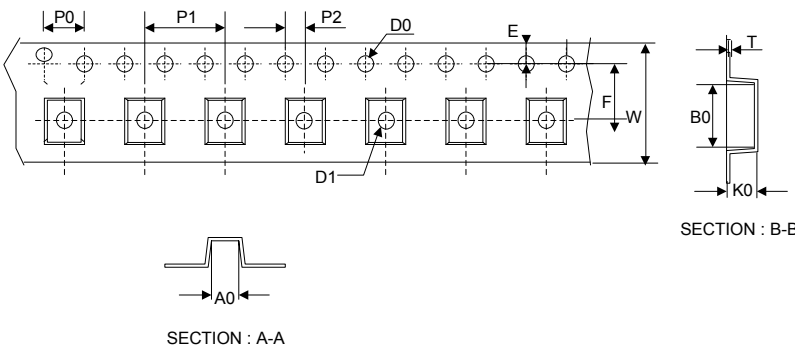
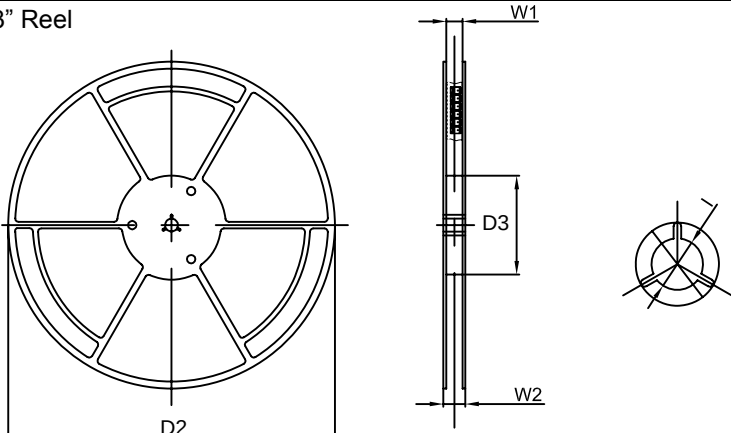


Dimensions in inches and (millimeters)



Dimensions	Value (in mm)
C	4.55
X	1.50
X1	5.80
Y	2.70
Y1	6.00
Y2	10.90

Tape & reel specification

Tape		Symbol	Dimension (mm)
		P0	4.00±0.20
		P1	8.00±0.20
		P2	2.00±0.20
		D0	1.55±0.15
		D1	1.55±0.20
		E	1.75±0.20
		F	7.50±0.20
		W	16.00±0.20
		A0	7.10±0.20
		B0	10.50±0.20
		K0	2.70±0.20
		T	0.30±0.10
		D2	330.0±5.0
13" Reel		Symbol	Dimension (mm)
		D3	100.0±4.0
		W1	20.0±5.0
		W2	25.0±5.0
		I	13.0±2.0
		Quantity: 2500PCS	